



NEWS RELEASE

Credo to Showcase Broad Portfolio of Connectivity Solutions for AI Scale-Out and Scale-Up Fabrics at 2026 OCP Global Summit

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SAN JOSE, Calif.--(BUSINESS WIRE)-- **Credo Technology Group Holding Ltd** (Credo) (NASDAQ: CRDO), an innovator in providing connectivity at scale through fast, reliable, and energy-efficient system solutions, will showcase its newest optical and copper interconnect products for scaling AI infrastructure at OCP Global Summit 2026, which takes place October 12-15 at the San Jose Convention Center.

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Credo Booth
Demonstration Highlights
(Booth B2, October 13-15)

- **Micro-Emitter NPO Enabled Optical Backplane for Scale-Up:** Through collaboration with SENKO, Credo has developed a high-reliability micro-emitter blind-mate optical backplane architecture that delivers up to 10x higher bandwidth compared to the latest copper backplanes.
- **1.6T ZeroFlap Active Light Cable (ALC):** Closes a mid-reach gap between copper's distance limits and the power and cost overhead of traditional pluggable optics.
- **1.6T ZeroFlap Optics:** Transceivers featuring Credo's latest ZeroFlap DSP and integrated silicon photonics, paired with real-time link telemetry through the Credo **PILOT** observability platform.
- **1.6T ZeroFlap Active Electrical Cable (AEC):** Advanced AEC solution delivering high-speed AI interconnects with real-time functional testing, diagnostics, and fault analysis through PILOT.
- **Toucan Gen6 PCIe AEC:** PCIe rack-level connectivity solution for GPU-intensive AI workloads, using PILOT to provide real-time telemetry and rapid fault isolation; demonstrated on the CWF Intel platform.

- **OmniConnect Weaver:** Credo's FPGA-implementation of its memory fanout gearbox (Weaver), breaking the AI inference memory wall; demonstrated with a live, interactive GUI.
- **1.6T Cardinal DSP + SiPho Integration:** A fully integrated optical module pairing Credo's 1.6T Cardinal DSP with an in-house Silicon Photonics PIC, demonstrating multi-vendor live interoperability.

Featured Sessions:

- **Executive Session with Credo President and CEO Bill Brennan**
Wider. Slower. Better: Optics That Can Beat Copper
October 12 at 3:20 p.m. – Lower Level – LL21DE
- **Expo Hall Session with Credo AVP of Product LK Bhupathi**
Going Wide: Scalable and Reliable Optical Interconnects for AI Clusters
October 13 at 3:30 p.m. – Concourse Level – Expo Hall Theater

Presentations:

- **More Signal, Less Noise: Improving AI Cluster Returns Through Standardized Transceiver Telemetry in the OCP Optics Reliability Workstream**
October 13 at 2:05 p.m. – Concourse Level – 210AE
Chris Collins, Credo AVP of Sales & Optical Product Marketing, Credo
- **Extending Community SONiC for Advanced Optics Telemetry Aligned with OCP Standards**
October 14 at 3:40 p.m. – Concourse Level – 230A
Rajan Pai, VP of Optical Solutions, Credo
- **An Open Lightweight Serial Interconnect for Composable AI Architectures**
October 15 at 2:15 p.m. – Concourse Level – 211
Vishal Shah, VP of Product, Credo
Allan Cattle, CEO, Nallasway

To request a meeting or product demo, please contact sales@credosemi.com.

About Credo

Credo's mission is to transform connectivity at scale through fast, reliable, and energy-efficient system solutions. Our high-speed copper and optical interconnect technologies deliver industry-leading power and performance from chip to cluster to meet the ever-expanding data infrastructure demands of AI.

Our vertically integrated connectivity portfolio is comprised of our flagship purple ZeroFlap (ZF) Active Electrical Cables (AECs) and ZF optical transceivers; optical components including silicon photonics-based photonic integrated

circuits (SiPho PICs) and DSPs; OmniConnect AI memory and chip-to-chip interconnect; and retimers for Ethernet and PCIe—supported by our PILOT diagnostic and analytics software platform. Credo innovations enable our customers to connect the systems that connect the world.

For more information, please visit <https://www.credosemi.com>. Follow Credo on **LinkedIn**.

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